# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

## Marketing Name / Model
[List multiple models if applicable.]

| HP Pro Tablet 608 G1 |

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of Items Included in Product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm MB, WLAN</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Battery cell</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01)
Components and waste containing asbestos
Components, parts and materials containing refractory ceramic fibers
Components, parts and materials containing radioactive substances

2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td>#1</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Use suction cups to disassemble Rear Cover
2. Remove screw to disassemble Battery BKT / Battery connector / Wifi-Main cable head
3. Remove screw at MB & Audio Board area to disassemble Audio Board BKT
4. Disassemble the LTE cable head and the black tape
5. Remove screw to disassemble Wifi-Aux antenna
6. Disassemble the Cu-foil at camera connector and L/R speaker connector
7. Disassemble the mylar at camera connector & Wwan card
8. Disassemble Power FPC
9. Disassemble the P-SENSOR
10. Disassemble Vibration Motor
11. Disassemble screw & L/R speaker ; Disassemble sponge at L speaker
12. Disassemble Front / Rear camera
13. Disassemble Touch screen board
14. Disassemble screw to disassemble POGO IN BKT & LVDS BKT
15. Disassemble LVDS connector & PC Mylar
16. Disassemble POGO IN connector & Wifi-Main antenna
17. Disassemble LTE-Aux Cable & Black Tape
18. Pull Battery Adhesive & Disassemble Battery
19. Disassemble screw at MB
20. Disassemble Audio Board FPC / Audio Board / MB
21. Disassemble Audio Board FPC
22. Disassemble the LTE-Aux & R-Speaker
23. Disassemble Gasket & P-SENSOR
24. Disassemble LTE-MAIN antenna from L-Speaker & Cu-foil
25. Disassemble screw
26. Disassemble screw & Thermal PAD
27. Disassemble Middle Plate
28. Disassemble Power FPC & Rubber
29. Disassemble Power Button & Volume Button
30. Disassemble Frame ring
31. Disassemble POGO IN

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

PSG instructions for this template are available at EL-MF877-01
3.2.0 Total

3.2.1 Use suction cups to disassemble Rear Cover

3.2.2 Remove screw to disassemble Battery BKT / Battery connector / Wifi-Main cable head
3.2.3 Remove screw at MB & Audio Board area to disassemble Audio Board BKT

3.2.4 Disassemble the LTE cable head and the black tape
3.2.5 Remove screw to disassemble Wifi-Aux antenna

3.2.6 Disassemble the Cu-foil at camera connector and L/R speaker connector

3.2.7 Disassemble the mylar at camera connector & Wwan card

3.2.8 Disassemble Power FPC
3.2.9 Disassemble the P-SENSOR

3.2.10 Disassemble Vibration Motor

3.2.11 Disassemble screw & L/R speaker ; Disassemble sponge at L speaker.
3.2.12 Disassemble Front / Rear camera

3.2.13 Disassemble Touch screen board
3.2.14 Disassemble screw to disassemble POGO IN BKT & LVDS BKT

3.2.15 Disassemble LVDS connector & PC Mylar

3.2.16 Disassemble POGO IN connector & Wifi-Main antenna
3.2.17 Disassemble LTE-Aux Cable & Black Tape

3.2.18 Pull Battery Adhesive & Disassemble Battery
3.2.19 Disassemble screw at MB

3.2.20 Disassemble Audio Board FPC / Audio Board / MB

3.2.21 Disassemble Audio Board FPC
3.2.22 Disassemble the LTE-Aux & R-Speaker

3.2.23 Disassemble Gasket & P-SENSOR
3.2.24 Disassemble LTE-MAIN antenna from L-Speaker & Cu-foil

3.2.25 Disassemble screw
3.2.26 Disassemble screw & Thermal PAD

3.2.27 Disassemble Middle Plate
3.2.28 Disassemble Power FPC & Rubber

![Image of Power FPC and Rubber Disassembly]

3.2.29 Disassemble Power Button & Volume Button

![Image of Power Button and Volume Button Disassembly]
3.3.30 Disassemble Frame ring

3.3.31 Disassemble POGO IN